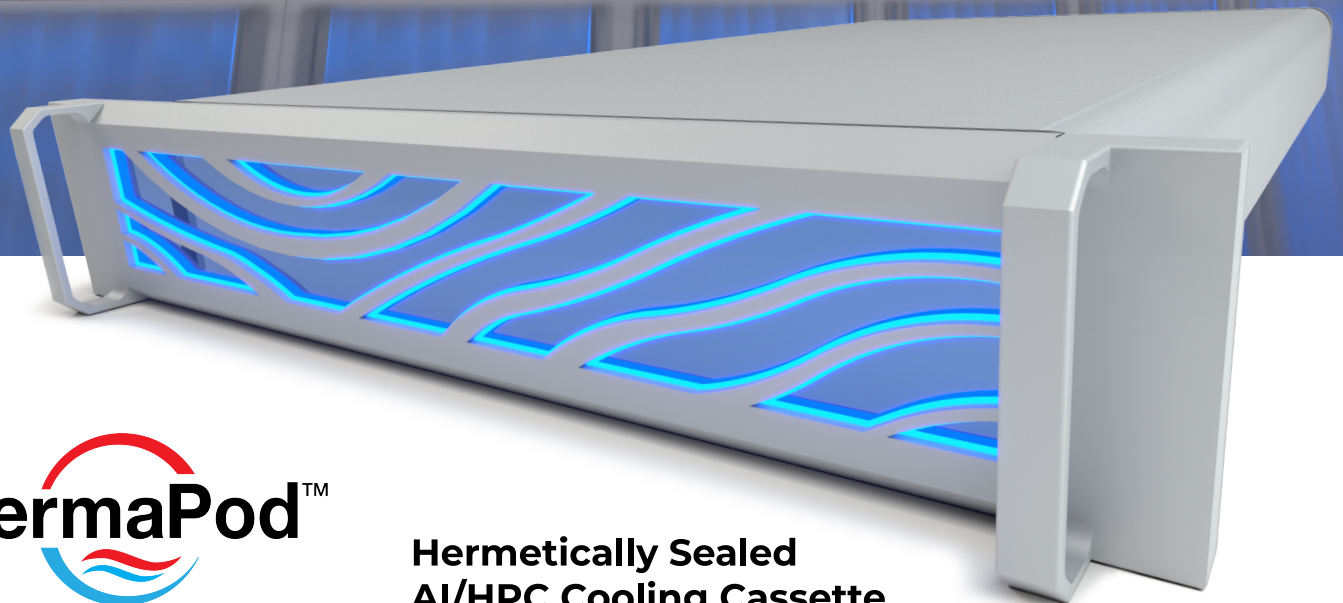# THE BEST WAY TO BE COOL

The ThermaPod™ Cooling Cassette

ThermaPod™

**Hermetically Sealed
AI/HPC Cooling Cassette
Versatile, Scalable, and Future-Proof.**

# ThermaPod™ – Adaptable AI/HPC Cooling

System Purpose

A hermetically sealed cooling cassette that is capable of operating in multiple cooling modes. ThermaPod design target:

15–25 kW per 2U (mode-dependent)

Designed for Facility-to-Chip™ integration, supporting single-phase and two-phase cooling. Configurable for immersion, spray, or direct-to-chip thermal transfer.

Modes & Panel Role

1. **Two-Phase Immersion –**
   Roof = primary condenser; other panels assist.

2. **Two-Phase Spray**
   Roof = primary condenser; other panels assist.

3. **Direct-to-Chip (Indirect)**
   Roof = micro AC; other panels manage liquid cooling.
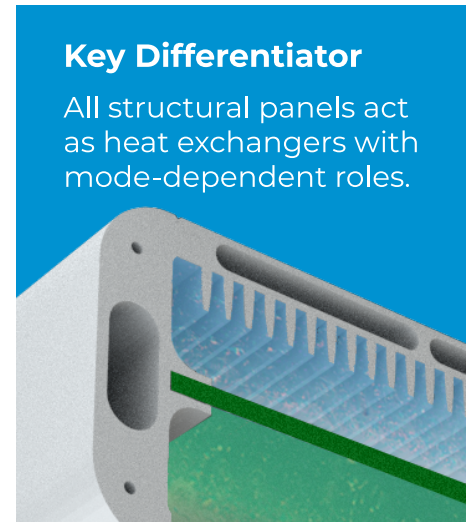
Key Differentiator

All structural panels act as heat exchangers with mode-dependent roles.

Anodized Aluminum body is hermetically sealed.

AI/HPC circuitry may be cooled using conventional cold plates.

AI/HPC circuitry is captured inside a cool chamber.

Endcaps control fluid direction, input, and output.

All structural panels are engineered with internal channels for heat transfer throughout the ThermaPod™ Cooling Cassette.

All Graphic content created by Jeff Rhodes, Industrial-Designs.com.